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- (81) 指定国(除另有指明, 要求每一种可提供的国家保护): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW。

(54) Title: WAFER POLISHING SYSTEM

(54) 发明名称: 一种晶圆抛光系统

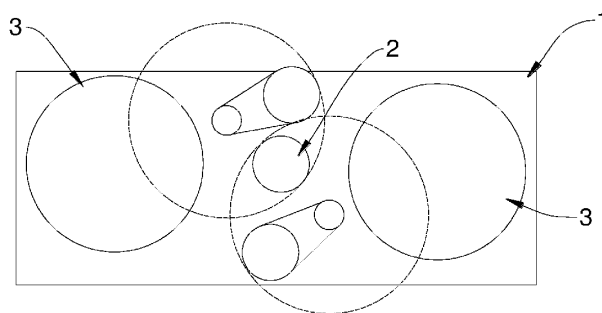


图 2

(57) Abstract: Disclosed in the present invention is a wafer polishing system, at least comprising a polishing unit, which comprises a fixed working station and two polishing modules, wherein the polishing modules are located on two sides of the fixed working station; each polishing module comprises a polishing platform and a polishing arm, which can drive a wafer to move relative to the polishing platform, so as to implement a polishing process; the polishing arms of the polishing modules on the two sides are located in a diagonal direction of the fixed working station; and the polishing arms can respectively swing between the fixed working station and the polishing platforms to transfer the wafer, and movement regions of the polishing arms having an overlapping portion. By means of the present invention, the polishing arm of each polishing module is independently controlled, so as to achieve better stability and flexibility; and only one fixed working station is needed to achieve the cooperation of multiple polishing modules to implement the polishing process of single or multiple wafers, so that the movement path in the polishing process is greatly shortened, which minimizes the time of the transfer process and improves the polishing efficiency.

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(84) 指定国(除另有指明, 要求每一种可提供的地区保护): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW), 欧亚 (AM, AZ, BY, KG, KZ, RU, TJ, TM), 欧洲 (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG)。

本国际公布:

— 包括国际检索报告(条约第21条(3))。

(57) 摘要: 本发明公开了一种晶圆抛光系统, 至少包括一个抛光单元; 抛光单元包括一个固定工作位, 及两个抛光模组, 抛光模组位于固定工作位的两侧; 抛光模组包括抛光平台和抛光臂, 抛光臂可带动晶圆相对抛光平台活动, 以实现抛光工艺; 两侧抛光模组的抛光臂位于固定工作位的斜对角方向, 抛光臂分别可在固定工作位和抛光平台之间摆动实现晶圆的转移, 且抛光臂的活动区域具有重叠部分。本发明每个抛光模组的抛光臂独立控制, 稳定性更好, 灵活度更高; 仅仅需要一个固定工作位就可以实现多个抛光模组配合实现单个或多个晶圆的抛光工艺, 抛光过程的移动路径大大缩短, 使得传输过程时间最小化, 抛光效率更高。